Repetition: Refractive Index



The real part of the refractive index corresponds to refractive index n, as it appears in Snellius law of refraction.

The imaginary part corresponds to the absorption of energy in the medium.

Repetition: Optics - Conservation Law

For optics the following conservation law is valid:

T + R + A + S = 1

- T ... Transmission R ... Reflection
- A ... Absorption
- A ... Absorption
- S ... Scattering

For geometric optics the refraction index n can be considered as frequency independent.

Repetition: Optics - Interfaces



Reflection: $\alpha = \alpha'$

Refraction:

$$\frac{\sin\alpha}{\sin\beta} = \frac{n_2}{n_1}$$

Wavelength:

$$\lambda_i = \frac{\lambda_{Vak}}{n_i}$$

Repetition: Fresnel's Equations 2 Media, indices of refraction n_1 , n_2 , perpendicular impingement, i. e.: $\varphi_1 = \varphi_2 = 0^\circ$

Reflection:

$$r_k^p = r_k^n = \frac{n_1 - n_2}{n_1 + n_2}$$

Transmission:

$$t_k^p = t_k^n = \frac{2n_1}{n_1 + n_2}$$

Repetition: Optical Film Thickness

Electromagnetic radiation passes from Vacuum into a Medium with refractive index n:

Frequency ω:

$$\omega_{n} = \omega_{Vak}$$
$$\lambda_{n} = \frac{\lambda_{Vak}}{n}$$

Wavelength λ :

If a film thickness is given as the multiple of a wavelength, λ_n is meant. This film thickness is called "optical film thickness", d_{opt}.

$$d_{Opt} = n \cdot d$$

It is:

Repetition: Reflection Suppression



Intensities of reflected radiation:

$$I_{r}^{0} = \frac{(n_{0} - n_{1})^{2}}{(n_{0} + n_{1})^{2}} \quad I_{r}^{2} = \frac{(n_{1} - n_{2})^{2}}{(n_{1} + n_{2})^{2}}$$
$$I_{r}^{0} = I_{r}^{2} \Longrightarrow n_{1} = \sqrt{n_{0} \cdot n_{2}}$$

Amplitude requirement

Repetition: Single Layer



Repetition: Reflection Enhancement I



Repetition: Reflection Enhancement II

A dielectric mirror consists of a multilayer made from $\lambda/4$ -coatings with alternating high (H) and low (L) indices of refraction.

Anzahl der Schichten	Reflexion in %			
	$n_{\rm L} = 1,38$ $n_{\rm H} = 2,3$ $n_{\rm s} = 1,51$	$n_{\rm L} = 1,47$ $n_{\rm H} = 2,3$ $n_{\rm s} = 1,51$		
3	53,89	53,23		
5	85,20	80,84		
7	94,67	92,15		
9	98,08	96,79		
11	99,31	98,68		
13	99,75	99,46		
15	99,91	99,78		
17	99,97	99,91		
19	99,99	99,63		

Magnetic Properties I

Motivation: permanent data storage



Longitudinal Recording

Perpendicular Recording

Magnetic Properties II

Motivation: volatile data storage





Spin Valve

Magnetic Random Access Memory (MRAM)

Switching

"Switching" of a magnetic element means the complete reversal of the magnetization M by an external field H. To obtain the equilibrium position of M in dependence on H, the total energy E resulting from the relative orientation of M and H has to be minimized.

Energy contributions:

- External field
- Stray field
- Anisotropy
- Exchange energy
- Domain walls



From Computer Desktop Encyclopedia

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Energy Contributions



Grafik: Arbeitsgruppe Mikromagnetismus, T. Schrefl http://magnet.atp.tuwien.ac.at/

Energy Consideration I

Focus on the energy contributions from:

- External field
- Anisotropy



Magnetization considered to rotate coherently!

Energy Consideration II

Total magnetic energy (referred to unit volume); anisotropy constant K:





H parallel to easy direction:



A hysteresis loop is observable.

$$H_{\rm K} = \frac{2 \cdot \rm K}{\left|\rm M\right|}$$

External Coercitivity H_K

Magnetic Reversal II

H perpendicular to easy direction:



There is no hysteresis loop. M turns continously. Each intermediate position is stable.

Further Considerations

Magnetic reversal may not occur via coherent rotation of M in all cases. Further influences:

- Domain nucleation
- Domain wall mobility
- Volume of magnetized regions
- → Superparamagnetic limit:

Volumes of magnetized regions (bit size) can become so small, that the anisotropy energy can be surpassed by thermal fluctuations → instability

Superparamagnetic Limit

Estimate:

Typical anisotropy energies:

$$E_{Anis} = 10^4 - 10^5 \text{ J} \cdot \text{m}^{-3}$$

Thermal energy within a grain of volume V:

$$k_{B} \cdot T = E_{Anis} \cdot V \Longrightarrow V = l^{3} = \frac{k_{B} \cdot T}{E_{Anis}} \Longrightarrow l = \sqrt[3]{\frac{k_{B} \cdot T}{E_{Anis}}}$$

T = 300K : 1 = 7.5 - 3.5 nm Giant Magneto Resistance (GMR)

Magneto Resistance is the phenomenon that the electric resistivity can be influenced by the direction of the magnetization.

The effect is based on different scattering probabilities between electrons of equal and opposite spins. It has extremely important technological and scientific applications (Nobel prize 2007!):

Hard disk reading heads

Spin valves

Chemical Composition

- For the chemical analysis of thin films as well as for the analysis of the surface of bulk materials a wide range of physical analysis methods is available. Most of these methods are based on the following principle:
 - + Bombardement of the material with probe particles
 - + Detection of the generated radiation or of the generated particles

Only electron optic methods (TEM, LEED, RHEED) and scanning probe methods (STM, AFM, ...) do not necessarily involve this principle.

Physical Analytics - Survey

Anregung durch		Nachweis durch						
		Photonen		Elektronen		Ionen		
		optisch	Röntgen					
Photonen	optisch	AA UV IR		ESCA	UPS	LIMA		
	Röntgen		XRF XRD		XPS			
Elektronen			ЕРМ	SEM TEM STM	AES SAM LEED RHEED			
Ionen		SCANIIR	ШΧ			SIMS SNMS ISS	IPM RBS	

Erklärung der Abkürzungen:

- AA Atomic Absorption
- AES Auger Electron Spectroscopy
- EPM Electron Probe Microanalysis
- ESCA Electron Spectroscopy for Chemical Analysis
- IIX Ion Induced X-Rays
- IPM Ion Probe Microanalysis
- IR Infrared Spectroscopy
- ISS Ion Scattering Spectroscopy
- LEED Low Energy Electron Diffraction
- LIMA Laser induced Ion Mass Analyzer
- RBS Rutherford Backscattering Spectroscopy
- RHEED Reflexion High Energy Electron Diffraction
- SAM Scanning Auger Microanalysis
- SCANIIR Surface Composition Analysis by Neutral and Ion Impact Radiation
- SEM Scanning Electron Microscopy
- SIMS Secondary Ion Mass Spectrometry
- SNMS Secondary Neutrals Mass Spectrometry
- STM Scanning Tunnel Microscopy
- TEM Transmission Electron Microscopy
- UPS UV-Photoelectron Spectroscopy
- UV UV-Spectroscopy
- XPS X-Ray Photoelectron Spectroscopy
- XRD X-Ray Diffraction
- XRF X-Ray Fluorescence Spectroscopy

Electron Beam Micro Analysis



Interaction volumes:

Backscattered electrons: approx. 1-5µm ejection depth Secondary electrons: near surace region Auger electrons: approx. 10 mn ejection depth X-rays: approx. 1-5µm ejection depth

Auger Electron Spectroscopy (AES)



- + Surface sensitive (ejection depth 1 10 nm)
- + Sensitive to light elements
- + Sensitivity limit: approx. 0.1 At%

Energy Cispersive X-Ray Analysis (EDX)

Ejection volume



Detection limit: ca. 0.1 At%

XPS, UPS

Photoelectron spectroscopy by excitation with X-rays (XPS) or UV-radiation (UPS)

Observable properties:

- + Electron work function
- + Density of states

Electron Energy Loss Spectroscopy

- + High lateral resolution (TEM)
- + Sensitivity limit: ca. 1 at%
- + Possibility of local chemical mapping

SIMS, SNMS

Secondary Ion Mass Spectroscopy (SIMS) or Secondary Neutral Mass Spectroscopy (SNMS): Mass spectroscopy of directly sputtered ions (SIMS) or post ionized neutrals (SNMS):

Caution:

Ionization cross section within the bulk does not correspond to the one of a single atom " matrix effect "

- + High chemical sensitivity (mass spectroscopy)
- + Quantification possible (SNMS)
- + Sensitivity limit: ppm

LEISS

Low Energy Ion Surface Spectroscopy

- + High surface sensitivity (1. Monolayer)
- + Absolute quantification possible (simple collision mechanism)

GDOS

Glow Discharge Optical Spectroscopy

- + Fast depth profiling
- + Good chemical sensitivity
- + Reasonable quantification possible (Spectroscopy)

RBS Rutherford Backscattering

+ Quantification possible (Coulomb potential)

LEED

Low Energy Electron Diffraction

- + Surface sensitive
- + Yields surface crystallography and adsorbate positions

RHEED

Reflected High Energy Electron Diffraction

Ideal situation:

- + Surface sensitive
- + Yields detailed informations about growth modes (Layer By Layer/roughening/stochastic)